1. SCOPE

This specification covers the requirements for application of AMP* PN 63066 printed circuit board .032 \times .250 tab. These requirements are applicable to automatic machine application tooling only.

2. NOMENCLATURE

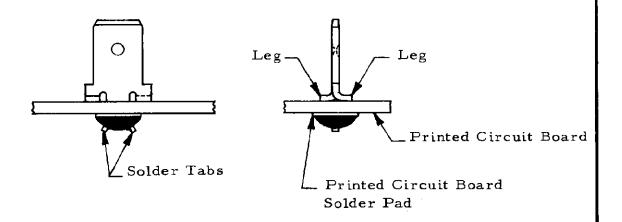


Figure 1

3. REQUIREMENTS

3.1. Printed Circuit Board

- A. Thickness shall be . 062 nominal.
- B. Hole diameter shall be .100 \pm .002 Dia.

*Trademark of AMP Incorporated.

⊕I #⊃					CHK Delive	AMP INCORPORATED Harrisburg, Pa.					
					Jon Fortun	, ,	LOC B	Α	^{NO} 4-	2058	REV A
- North				ļ	SHEET	TAB, .032 X .250, PRINTED CIRCUIT BOARD, PN 63066, APPLICATION OF					
015T	A LTR	Revise Figure 2	APP	10-28 -82	1 OF <u>3</u>						

3.2. Insertion

Tab installation requirements shall be as indicated in Figure 2 after insertion and clinching.

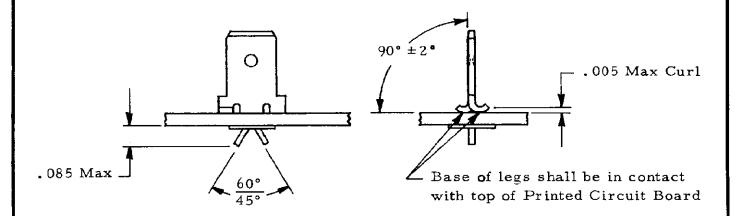


Figure 2

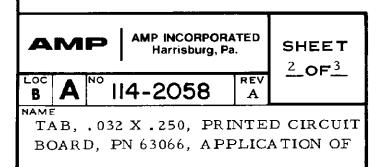
3.3. Soldering and Cleaning

A. Flux Selection

Solder tabs shall be fluxed prior to soldering by use of a medium active rosin base flux or a medium to highly active organic flux. Selection of the proper flux will depend on customer's type of printed circuit board and other components, if any, mounted on the board. Also, the choice of flux would have to be compatible to customer's flow solder line, as well as manufacturing and safety requirements.

B. Cleaning

Removal of fluxes, residues and activators is mandatory. Cleaning procedures would again be the choice of the customer and would depend on the type of flux used on his solder line.



C. Soldering Guideline

AMP Corporate Bulletin No. 52 is available upon request and can be used as a guide in soldering. This bulletin gives various flux types and characteristics along with the commercial designation and flux removal procedures. A check list is attached to the bulletin and is intended to serve as a guide for obtaining information from customers having soldering problems.

3.4. Workmanship

There shall be no deformation of the tab during the insertion and clinching operation that will affect the performance.

